

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto; and
at least one stabilizer protruding from ~~said~~the surface and positioned between a periphery of ~~said~~the surface and each contact pad exposed to ~~said~~the surface and including a plurality of at least partially superimposed, contiguous, mutually adhered layers of the same type of dielectric material.
2. (Currently amended) The semiconductor device component of claim 1, wherein ~~said~~the at least one stabilizer protrudes from ~~said~~the surface a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of ~~said~~the contact pads will extend beyond ~~said~~the surface.
3. (Currently amended) The semiconductor device component of claim 2, wherein ~~said~~the at least one stabilizer protrudes from ~~said~~the surface a distance that permits conductive structures on ~~said~~the contact pads to contact conductors of another semiconductor device component upon assembly of ~~said~~the substrate with ~~said~~the another semiconductor device component such that ~~said~~the surface of ~~said~~the assembly faces a conductor-bearing surface of ~~said~~the another semiconductor device component.
4. (Canceled)
5. (Currently amended) The semiconductor device component of claim 1, wherein ~~said~~the at least one stabilizer comprises a photocurable material.

6. (Canceled)

7. (Currently amended) The semiconductor device component of claim 1, wherein ~~said~~the at least one stabilizer is positioned proximate a corner of ~~said~~the surface.

8. (Currently amended) The semiconductor device component of claim 1, wherein ~~said~~the at least one stabilizer has a cross-sectional shape of one of quadrilateral, round, oval, and triangular.

9. (Currently amended) The semiconductor device component of claim 1, wherein ~~said~~the at least one stabilizer is elongated in a direction parallel to ~~said~~the surface.

10. (Currently amended) The semiconductor device component of claim 1, further comprising protruding conductive structures in contact with selected ones of ~~said~~the contact pads.

11. (Currently amended) The semiconductor device component of claim 10, wherein ~~said~~the conductive structures comprise at least one of solder bumps, conductive columns, conductor-filled columns, and z-axis conductive adhesive.

12. (Currently amended) The semiconductor device component of claim 1, wherein ~~said~~the substrate comprises a semiconductor wafer with a plurality of dice thereon.

13. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, ~~said~~the contact pads being configured to be connected with conductors on a surface of another semiconductor device component; and
at least one stabilizer protruding from ~~said~~the surface of ~~said~~the substrate and positioned between a periphery of ~~said~~the surface and ~~said~~the contact pads, ~~said~~the at least one stabilizer

comprising a plurality of superimposed, contiguous, mutually adhered layers, each of which comprises dielectric material.

14. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer protrudes from ~~said~~the surface of ~~said~~the substrate a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of ~~said~~the contact pads will extend beyond ~~said~~the surface.

15. (Currently amended) The semiconductor device component of claim 14, wherein ~~said~~the at least one stabilizer protrudes from ~~said~~the surface of ~~said~~the substrate a distance that permits conductive structures on ~~said~~the contact pads to contact ~~said~~the conductors of ~~said~~the another semiconductor device component.

16. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer comprises a dielectric material.

17. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer comprises a photocurable material.

18. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer is positioned proximate a corner of ~~said~~the surface of ~~said~~the substrate.

19. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer has a cross-sectional shape of one of quadrilateral, round, oval, and triangular.

20. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer is elongated in a direction parallel to ~~said~~the surface.

21. (Currently amended) The semiconductor device component of claim 13, further comprising protruding conductive structures in contact with selected ones of ~~said~~the contact pads.

22. (Currently amended) The semiconductor device component of claim 21, wherein ~~said~~the conductive structures comprise at least one of solder bumps, conductive columns, conductor-filled columns, and z-axis conductive adhesive.

23. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the substrate comprises a semiconductor wafer with a plurality of dice thereon.

24. (Currently amended) The semiconductor device component of claim 13, wherein ~~said~~the at least one stabilizer maintains a substantially uniform distance between ~~said~~the surface of ~~said~~the substrate and ~~said~~the surface of ~~said~~the another semiconductor device component.

25. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, ~~said~~the contact pads being configured to be connected with conductors on a first surface of another semiconductor device component, each contact pad of the semiconductor device component being arranged substantially in-line with a plurality of other contact pads and positioned proximate to a center line of ~~said~~the substrate; and
at least one nonconductive stabilizer protruding from ~~said~~the surface of ~~said~~the substrate and positioned between a periphery of ~~said~~the surface and ~~said~~the contact pads, ~~said~~the at least one nonconductive stabilizer comprising an elongate element which extends in a direction parallel to ~~said~~the surface of ~~said~~the substrate.

26. (Currently amended) The semiconductor device component of claim 25, wherein ~~said~~the at least one stabilizer is configured so that voids do not occur in an insulative underfill

material when ~~said~~the insulative underfill material is flowed into a space created when ~~said~~the substrate is connected with ~~said~~the another semiconductor device component.

27. (Currently amended) The semiconductor device component of claim 25, wherein ~~said~~the at least one stabilizer protrudes from ~~said~~the surface of ~~said~~the substrate a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of ~~said~~the contact pads will extend beyond ~~said~~the surface.

28. (Currently amended) The semiconductor device component of claim 27, wherein ~~said~~the at least one stabilizer protrudes from ~~said~~the surface a distance that permits conductive structures on ~~said~~the contact pads to contact ~~said~~the conductors of ~~said~~the another semiconductor device component.

29. (Currently amended) The semiconductor device component of claim 25, wherein ~~said~~the at least one stabilizer comprises a dielectric material.

30. (Currently amended) The semiconductor device component of claim 25, wherein ~~said~~the at least one stabilizer comprises a photocurable material.

31. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, the contact pads being arranged substantially in-line with one another and positioned proximate to a center line of the substrate; and
at least one stabilizer protruding from ~~said~~the surface, comprising an elongate structure which extends in a direction parallel to a plane of ~~said~~the surface, and being positioned between a periphery of ~~said~~the surface and ~~said~~all of the contact pads.

32. (Canceled)